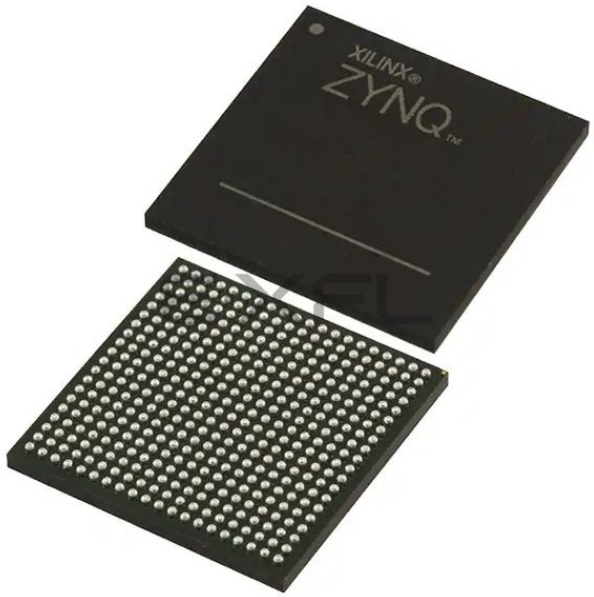

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What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details	
Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	766MHz
Primary Attributes	Artix™-7 FPGA, 28K Logic Cells
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	400-LFBGA, CSPBGA
Supplier Device Package	400-CSPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc7z010-2clg400i

Table 2: **Recommended Operating Conditions(1)(2) *(Cont'd)***

Symbol	Description	Min	Typ	Max	Units
V_{PIN}(4)	PS DDR and MIO I/O input voltage	–0.20	–	V_{CCO_DDR} + 0.20 V_{CCO_MIO} + 0.20	V
PL					
V_{CCINT}(5)	PL internal supply voltage	0.95	1.00	1.05	V
	PL -1LI (0.95V) internal supply voltage	0.92	0.95	0.98	V
V_{CCAUX}	PL auxiliary supply voltage	1.71	1.80	1.89	V
V_{CCBRAM}(5)	PL block RAM supply voltage	0.95	1.00	1.05	V
	PL -1LI (0.95V) block RAM supply voltage	0.92	0.95	0.98	V
V_{CCO}(6)(7)	PL supply voltage for HR I/O banks	1.14	–	3.465	V
V_{IN}(4)	I/O input voltage	–0.20	–	V_{CCO} + 0.20	V
	I/O input voltage (when V_{CCO} = 3.3V) for V_{REF} and differential I/O standards except TMDS_33(8)	–0.20	–	2.625	V
I_{IN}(9)	Maximum current through any (PS or PL) pin in a powered or unpowered bank when forward biasing the clamp diode	–	–	10	mA
V_{CCBATT}(10)	Battery voltage	1.0	–	1.89	V
GTP Transceiver (XC7Z015 Only)					
$V_{MGTAVCC}$(11)	Analog supply voltage for the GTP transmitter and receiver circuits	0.97	1.0	1.03	V
$V_{MGTAVTT}$(11)	Analog supply voltage for the GTP transmitter and receiver termination circuits	1.17	1.2	1.23	V
XADC					
V_{CCADC}	XADC supply relative to GNDADC	1.71	1.80	1.89	V
V_{REFP}	Externally supplied reference voltage	1.20	1.25	1.30	V
Temperature					
T_j	Junction temperature operating range for commercial (C) temperature devices	0	–	85	°C
	Junction temperature operating range for extended (E) temperature devices	0	–	100	°C
	Junction temperature operating range for industrial (I) temperature devices	–40	–	100	°C
	Junction temperature operating range for expanded (Q) temperature devices	–40	–	125	°C

Notes:

1. All voltages are relative to ground. The PL and PS share a common ground.
2. For the design of the power distribution system consult the *Zynq-7000 All Programmable SoC PCB Design Guide* (UG933).
3. Applies to both MIO supply banks V_{CCO_MIO0} and V_{CCO_MIO1}.
4. The lower absolute voltage specification always applies.
5. V_{CCINT} and V_{CCBRAM} should be connected to the same supply.
6. Configuration data is retained even if V_{CCO} drops to 0V.
7. Includes V_{CCO} of 1.2V, 1.5V, 1.8V, 2.5V, and 3.3V at ±5%.
8. See Table 11 for TMDS_33 specifications.
9. A total of 200 mA per PS or PL bank should not be exceeded.
10. V_{CCBATT} is required only when using bitstream encryption. If battery is not used, connect V_{CCBATT} to either ground or V_{CCAUX}.
11. Each voltage listed requires the filter circuit described in the *7 Series FPGAs GTP Transceiver User Guide* (UG482).

Table 3: **DC Characteristics Over Recommended Operating Conditions**

Symbol	Description	Min	Typ[1]	Max	Units
V_{DRINT}	Data retention V_{CCINT} voltage (below which configuration data might be lost)	0.75	–	–	V
V_{DRI}	Data retention V_{CCAUX} voltage (below which configuration data might be lost)	1.5	–	–	V
I_{REF}	PS_DDR_VREF 0/1, PS_MIO_VREF, and V_{REF} leakage current per pin	–	–	15	µA
I_L	Input or output leakage current per pin (sample-tested)	–	–	15	µA
C_{IN}[2]	PL die input capacitance at the pad	–	–	8	pF
C_{PIN}[2]	PS die input capacitance at the pad	–	–	8	pF
I_{RPU}	Pad pull-up (when selected) @ V_{IN} = 0V, V_{CCO} = 3.3V	90	–	330	µA
	Pad pull-up (when selected) @ V_{IN} = 0V, V_{CCO} = 2.5V	68	–	250	µA
	Pad pull-up (when selected) @ V_{IN} = 0V, V_{CCO} = 1.8V	34	–	220	µA
	Pad pull-up (when selected) @ V_{IN} = 0V, V_{CCO} = 1.5V	23	–	150	µA
	Pad pull-up (when selected) @ V_{IN} = 0V, V_{CCO} = 1.2V	12	–	120	µA
I_{RPD}	Pad pull-down (when selected) @ V_{IN} = 3.3V	68	–	330	µA
	Pad pull-down (when selected) @ V_{IN} = 1.8V	45	–	180	µA
I_{CCADC}	Analog supply current, analog circuits in powered up state	–	–	25	mA
I_{BATT}[3]	Battery supply current	–	–	150	nA
R_{IN_TERM}[4]	Thevenin equivalent resistance of programmable input termination to V_{CCO}/2 (UNTUNED_SPLIT_40)	28	40	55	Ω
	Thevenin equivalent resistance of programmable input termination to V_{CCO}/2 (UNTUNED_SPLIT_50)	35	50	65	Ω
	Thevenin equivalent resistance of programmable input termination to V_{CCO}/2 (UNTUNED_SPLIT_60)	44	60	83	Ω
n	Temperature diode ideality factor	–	1.010	–	–
r	Temperature diode series resistance	–	2	–	Ω

Notes:

1. Typical values are specified at nominal voltage, 25°C.
2. This measurement represents the die capacitance at the pad, not including the package.
3. Maximum value specified for worst case process at 25°C.
4. Termination resistance to a V_{CCO}/2 level.

Power Supply Requirements

Table 6 shows the minimum current, in addition to I_{CCQ}, that is required by Zynq-7000 devices for proper power-on and configuration. If the current minimums shown in Table 5 and Table 6 are met, the device powers on after all four PL supplies have passed through their power-on reset threshold voltages. The Zynq-7000 device must not be configured until after V_{CCINT} is applied. Once initialized and configured, use the Xilinx Power Estimator (XPE) spreadsheet tool (download at www.xilinx.com/power) to estimate current drain on these supplies.

Table 6: **Power-On Current for Zynq-7000 Devices**

Device	$I_{CCPINTMIN}$	$I_{CCPAUXMIN}$	$I_{CCDDRMIN}$	$I_{CCINTMIN}$	$I_{CCAUXMIN}$	I_{CCOMIN}	$I_{CCBRAMMIN}$	Units
XC7Z007S	$I_{CCPINTQ}$ +70	$I_{CCPAUXQ}$ +40	I_{CCDDRQ} + 100 mA per bank	I_{CCINTQ} +40	I_{CCAUXQ} +60	I_{CCOQ} + 90 mA per bank	$I_{CCBRAMQ}$ +40	mA
XC7Z012S	$I_{CCPINTQ}$ +70	$I_{CCPAUXQ}$ +40	I_{CCDDRQ} + 100 mA per bank	I_{CCINTQ} +130	I_{CCAUXQ} +60	I_{CCOQ} + 90 mA per bank	$I_{CCBRAMQ}$ +40	mA
XC7Z014S	$I_{CCPINTQ}$ +70	$I_{CCPAUXQ}$ +40	I_{CCDDRQ} + 100 mA per bank	I_{CCINTQ} +70	I_{CCAUXQ} +60	I_{CCOQ} + 90 mA per bank	$I_{CCBRAMQ}$ +40	mA
XC7Z010 XA7Z010	$I_{CCPINTQ}$ +70	$I_{CCPAUXQ}$ +40	I_{CCDDRQ} + 100 mA per bank	I_{CCINTQ} +40	I_{CCAUXQ} +60	I_{CCOQ} + 90 mA per bank	$I_{CCBRAMQ}$ +40	mA
XC7Z015	$I_{CCPINTQ}$ +70	$I_{CCPAUXQ}$ +40	I_{CCDDRQ} + 100 mA per bank	I_{CCINTQ} +130	I_{CCAUXQ} +60	I_{CCOQ} + 90 mA per bank	$I_{CCBRAMQ}$ +40	mA
XC7Z020 XA7Z020 XQ7Z020	$I_{CCPINTQ}$ +70	$I_{CCPAUXQ}$ +40	I_{CCDDRQ} + 100 mA per bank	I_{CCINTQ} +70	I_{CCAUXQ} +60	I_{CCOQ} + 90 mA per bank	$I_{CCBRAMQ}$ +40	mA

Table 7: **Power Supply Ramp Time**

Symbol	Description	Conditions	Min	Max	Units
$T_{VCCPINT}$	Ramp time from GND to 90% of V_{CCPINT}		0.2	50	ms
$T_{VCCPAUX}$	Ramp time from GND to 90% of V_{CCPAUX}		0.2	50	ms
T_{VCCO_DDR}	Ramp time from GND to 90% of V_{CCO_DDR}		0.2	50	ms
T_{VCCO_MIO}	Ramp time from GND to 90% of V_{CCO_MIO}		0.2	50	ms
T_{VCCINT}	Ramp time from GND to 90% of V_{CCINT}		0.2	50	ms
T_{VCCO}	Ramp time from GND to 90% of V_{CCO}		0.2	50	ms
T_{VCCAUX}	Ramp time from GND to 90% of V_{CCAUX}		0.2	50	ms
$T_{VCCBRAM}$	Ramp time from GND to 90% of V_{CCBRAM}		0.2	50	ms
$T_{VCCO2VCCAUX}$	Allowed time per power cycle for $V_{CCO} - V_{CCAUX} > 2.625V$ and $V_{CCO\_MIO} - V_{CCPAUX} > 2.625V$	$T_j = 125°C$(1)	–	300	ms
		$T_j = 100°C$(1)	–	500	
		$T_j = 85°C$(1)	–	800	
$T_{MGTAVCC}$	Ramp time from GND to 90% of $V_{MGTAVCC}$		0.2	50	ms
$T_{MGTAVTT}$	Ramp time from GND to 90% of $V_{MGTAVTT}$		0.2	50	ms

Notes:

1. Based on 240,000 power cycles with nominal V_{CCO} of 3.3V or 36,500 power cycles with worst case V_{CCO} of 3.465V.

PL I/O Levels

Table 10: **SelectIO DC Input and Output Levels(1)(2)**

I/O Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
HSTL_I	–0.300	V_{REF} – 0.100	V_{REF} + 0.100	V_{CCO} + 0.300	0.400	V_{CCO} – 0.400	8.00	–8.00
HSTL_I_18	–0.300	V_{REF} – 0.100	V_{REF} + 0.100	V_{CCO} + 0.300	0.400	V_{CCO} – 0.400	8.00	–8.00
HSTL_II	–0.300	V_{REF} – 0.100	V_{REF} + 0.100	V_{CCO} + 0.300	0.400	V_{CCO} – 0.400	16.00	–16.00
HSTL_II_18	–0.300	V_{REF} – 0.100	V_{REF} + 0.100	V_{CCO} + 0.300	0.400	V_{CCO} – 0.400	16.00	–16.00
HSUL_12	–0.300	V_{REF} – 0.130	V_{REF} + 0.130	V_{CCO} + 0.300	20% V_{CCO}	80% V_{CCO}	0.10	–0.10
LVCMOS12	–0.300	35% V_{CCO}	65% V_{CCO}	V_{CCO} + 0.300	0.400	V_{CCO} – 0.400	Note 3	Note 3
LVCMOS15	–0.300	35% V_{CCO}	65% V_{CCO}	V_{CCO} + 0.300	25% V_{CCO}	75% V_{CCO}	Note 4	Note 4
LVCMOS18	–0.300	35% V_{CCO}	65% V_{CCO}	V_{CCO} + 0.300	0.450	V_{CCO} – 0.450	Note 5	Note 5
LVCMOS25	–0.300	0.7	1.700	V_{CCO} + 0.300	0.400	V_{CCO} – 0.400	Note 4	Note 4
LVCMOS33	–0.300	0.8	2.000	3.450	0.400	V_{CCO} – 0.400	Note 4	Note 4
LVTTL	–0.300	0.8	2.000	3.450	0.400	2.400	Note 5	Note 5
MOBILE_DDR	–0.300	20% V_{CCO}	80% V_{CCO}	V_{CCO} + 0.300	10% V_{CCO}	90% V_{CCO}	0.10	–0.10
PCI33_3	–0.400	30% V_{CCO}	50% V_{CCO}	V_{CCO} + 0.500	10% V_{CCO}	90% V_{CCO}	1.50	–0.50
SSTL135	–0.300	V_{REF} – 0.090	V_{REF} + 0.090	V_{CCO} + 0.300	V_{CCO}/2 – 0.150	V_{CCO}/2 + 0.150	13.00	–13.00
SSTL135_R	–0.300	V_{REF} – 0.090	V_{REF} + 0.090	V_{CCO} + 0.300	V_{CCO}/2 – 0.150	V_{CCO}/2 + 0.150	8.90	–8.90
SSTL15	–0.300	V_{REF} – 0.100	V_{REF} + 0.100	V_{CCO} + 0.300	V_{CCO}/2 – 0.175	V_{CCO}/2 + 0.175	13.00	–13.00
SSTL15_R	–0.300	V_{REF} – 0.100	V_{REF} + 0.100	V_{CCO} + 0.300	V_{CCO}/2 – 0.175	V_{CCO}/2 + 0.175	8.90	–8.90
SSTL18_I	–0.300	V_{REF} – 0.125	V_{REF} + 0.125	V_{CCO} + 0.300	V_{CCO}/2 – 0.470	V_{CCO}/2 + 0.470	8.00	–8.00
SSTL18_II	–0.300	V_{REF} – 0.125	V_{REF} + 0.125	V_{CCO} + 0.300	V_{CCO}/2 – 0.600	V_{CCO}/2 + 0.600	13.40	–13.40

Notes:

1. Tested according to relevant specifications.
2. 3.3V and 2.5V standards are only supported in HR I/O banks.
3. Supported drive strengths of 4, 8, or 12 mA in HR I/O banks.
4. Supported drive strengths of 4, 8, 12, or 16 mA in HR I/O banks.
5. Supported drive strengths of 4, 8, 12, 16, or 24 mA in HR I/O banks.
6. For detailed interface specific DC voltage levels, see the *7 Series FPGAs SelectIO Resources User Guide* (UG471).

Table 11: **Differential SelectIO DC Input and Output Levels**

I/O Standard	V_{ICM}(1)			V_{ID}(2)			V_{OCM}(3)			V_{OD}(4)		
	V, Min	V, Typ	V, Max	V, Min	V, Typ	V, Max	V, Min	V, Typ	V, Max	V, Min	V, Typ	V, Max
BLVDS_25	0.300	1.200	1.425	0.100	–	–	–	1.250	–	Note 5		
MINI_LVDS_25	0.300	1.200	V_{CCAUX}	0.200	0.400	0.600	1.000	1.200	1.400	0.300	0.450	0.600
PPDS_25	0.200	0.900	V_{CCAUX}	0.100	0.250	0.400	0.500	0.950	1.400	0.100	0.250	0.400
RSDS_25	0.300	0.900	1.500	0.100	0.350	0.600	1.000	1.200	1.400	0.100	0.350	0.600
TMDS_33	2.700	2.965	3.230	0.150	0.675	1.200	V_{CCO}–0.405	V_{CCO}–0.300	V_{CCO}–0.190	0.400	0.600	0.800

Notes:

1. V_{ICM} is the input common mode voltage.
2. V_{ID} is the input differential voltage (Q–$\overline{Q}$).
3. V_{OCM} is the output common mode voltage.
4. V_{OD} is the output differential voltage (Q–$\overline{Q}$).
5. V_{OD} for BLVDS will vary significantly depending on topology and loading.
6. LVDS_25 is specified in Table 13.

To select the -1LI (PL 0.95V) speed specifications in the Vivado tools, select the **Zynq-7000** sub-family and then select the part name that is the device name followed by an *i* followed by the package name followed by the speed grade. For example, select the **xc7z020iclg484-1L** part name for the XC7Z020 device in the CLG484 package and -1LI (PL 0.95V) speed grade. The -1LI (PL 0.95V) speed specifications are not supported in the ISE tools.

A similar part naming convention applies to the speed specifications selection in the ISE tools for supported devices. See Table 16 for the subset of the Zynq-7000 devices supported in the ISE tools.

PS Performance Characteristics

For further design requirement details, refer to the *Zynq-7000 All Programmable SoC Technical Reference Manual* (UG585).

Table 17: **CPU Clock Domains Performance**

Symbol	Clock Ratio	Description	Speed Grade				Units
			-3	-2	-1C/-1I/-1LI	-1Q	
$F_{CPU\_6X4X\_621\_MAX}$(1)	6:2:1	Maximum CPU clock frequency	866	766	667	667	MHz
$F_{CPU\_3X2X\_621\_MAX}$		Maximum CPU_3X clock frequency	433	383	333	333	MHz
$F_{CPU\_2X\_621\_MAX}$		Maximum CPU_2X clock frequency	288	255	222	222	MHz
$F_{CPU\_1X\_621\_MAX}$		Maximum CPU_1X clock frequency	144	127	111	111	MHz
$F_{CPU\_6X4X\_421\_MAX}$(1)	4:2:1	Maximum CPU clock frequency	710	600	533	533	MHz
$F_{CPU\_3X2X\_421\_MAX}$		Maximum CPU_3X clock frequency	355	300	267	267	MHz
$F_{CPU\_2X\_421\_MAX}$		Maximum CPU_2X clock frequency	355	300	267	267	MHz
$F_{CPU\_1X\_421\_MAX}$		Maximum CPU_1X clock frequency	178	150	133	133	MHz

Notes:

1. The maximum frequency during BootROM execution is 500 MHz across all speed specifications.

Table 18: **PS DDR Clock Domains Performance**(1)

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
F_{DDR3_MAX}	Maximum DDR3 interface performance	1066	1066	1066	1066	Mb/s
F_{DDR3L_MAX}	Maximum DDR3L interface performance	1066	1066	1066	1066	Mb/s
F_{DDR2_MAX}	Maximum DDR2 interface performance	800	800	800	800	Mb/s
F_{LPDDR2_MAX}	Maximum LPDDR2 interface performance	800	800	800	800	Mb/s
F_{DDRCLK_2XMAX}	Maximum DDR_2X clock frequency	444	408	355	355	MHz

Notes:

1. All performance numbers apply to both internal and external V_{REF} configurations.

Table 19: **PS-PL Interface Performance**

Symbol	Description	Min	Max	Units
$F_{EMIOGEMCLK}$	EMIO gigabit Ethernet controller maximum frequency	–	125	MHz
$F_{EMIOSDCLK}$	EMIO SD controller maximum frequency	–	25	MHz
$F_{EMIOSPICLK}$	EMIO SPI controller maximum frequency	–	25	MHz
$F_{EMIOJTAGCLK}$	EMIO JTAG controller maximum frequency	–	20	MHz
$F_{EMIOTRACECLK}$	EMIO trace controller maximum frequency	–	125	MHz
F_{FTMCLK}	Fabric trace monitor maximum frequency	–	125	MHz
$F_{EMIODMACLK}$	DMA maximum frequency	–	100	MHz
F_{AXI_MAX}	Maximum AXI interface performance	–	250	MHz

PS Switching Characteristics

Clocks

Table 20: **System Reference Clock Input Requirements**

Symbol	Description	Min	Typ	Max	Units
$T_{JTPSCLK}$	PS_CLK RMS clock jitter tolerance	–	–	±0.5	%
$T_{DCPSCLK}$	PS_CLK duty cycle	40	–	60	%
$T_{RFPSCLK}$	PS_CLK rise and fall time	–	–	6	ns
F_{PSCLK}	PS_CLK frequency	30	–	60	MHz

Table 21: **PS PLL Switching Characteristics**

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
T_{LOCK_PSPLL}	PLL maximum lock time	60	60	60	60	µs
F_{PSPLL_MAX}	PLL maximum output frequency	2000	1800	1600	1600	MHz
F_{PSPLL_MIN}	PLL minimum output frequency	780	780	780	780	MHz

Resets

Table 22: **PS Reset Assertion Timing Requirements**

Symbol	Description	Min	Typ	Max	Units
T_{PSPOR}	Required PS_POR_B assertion time(1)	100	–	–	µs
T_{PSRST}	Required PS_SRST_B assertion time	3	–	–	PS_CLK Clock Cycles

Notes:

1. PS_POR_B needs to be asserted Low until T_{PSPOR} after PS supply voltages reach minimum levels.

The PS_POR_B deassertion must meet the following requirements to avoid coinciding with the secure lockdown window. Figure 1 shows the timing relationship between PS_POR_B and the last power supply ramp (V_{CCINT}, V_{CCBRAM}, V_{CCAUX}, or V_{CCO} in bank 0). T_{SLW} minimum and maximum parameters define the beginning and end, respectively, of the secure lockdown window relative to the last PL power supply reaching 250 mV. The PS_POR_B must not be deasserted within the secure lockdown window.

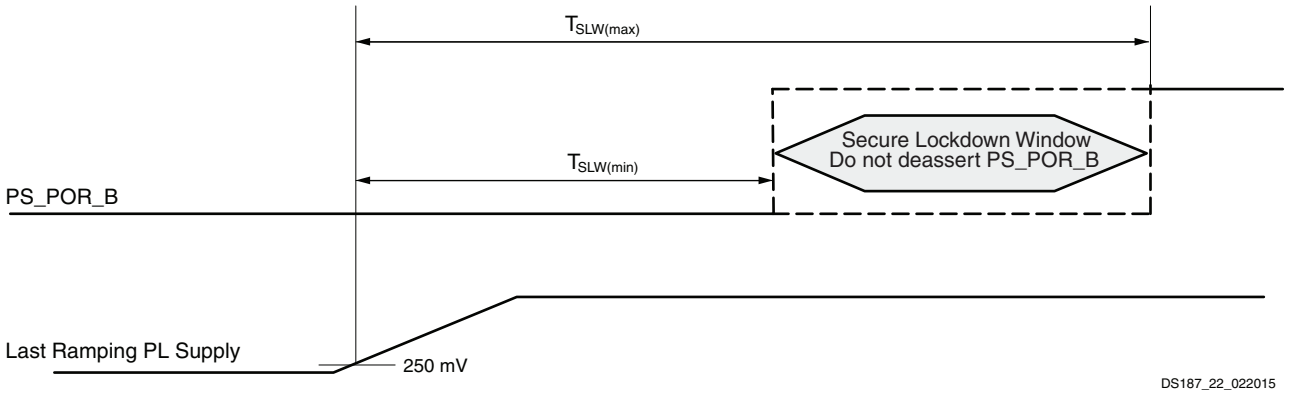

Figure 1: **PS_POR_B and Power Supply Ramp Timing Requirements**

Table 52: **IOB High Range (HR) Switching Characteristics *(Cont'd)***

I/O Standard	T_{IOPI}				T_{IOOP}				T_{IOTP}				Units
	Speed Grade				Speed Grade				Speed Grade				
	-3	-2	-1C/-1I/-1LI	-1Q	-3	-2	-1C/-1I/-1LI	-1Q	-3	-2	-1C/-1I/-1LI	-1Q	
HSTL_I_18_S	0.67	0.75	0.82	0.88	1.29	1.41	1.67	1.67	1.31	1.44	1.68	1.68	ns
HSTL_II_18_S	0.66	0.75	0.81	0.88	1.41	1.54	1.79	1.79	1.43	1.57	1.80	1.80	ns
DIFF_HSTL_I_S	0.68	0.76	0.83	0.86	1.59	1.71	1.96	1.96	1.60	1.74	1.98	1.98	ns
DIFF_HSTL_II_S	0.68	0.76	0.83	0.86	1.51	1.63	1.88	1.88	1.52	1.66	1.90	1.90	ns
DIFF_HSTL_I_18_S	0.71	0.79	0.86	0.86	1.38	1.51	1.76	1.76	1.40	1.54	1.77	1.77	ns
DIFF_HSTL_II_18_S	0.70	0.78	0.85	0.88	1.46	1.58	1.84	1.84	1.48	1.61	1.85	1.85	ns
HSTL_I_F	0.67	0.75	0.82	0.86	1.10	1.22	1.48	1.49	1.12	1.25	1.49	1.51	ns
HSTL_II_F	0.65	0.73	0.80	0.86	1.12	1.24	1.49	1.49	1.13	1.27	1.51	1.51	ns
HSTL_I_18_F	0.67	0.75	0.82	0.88	1.13	1.26	1.51	1.54	1.15	1.29	1.52	1.56	ns
HSTL_II_18_F	0.66	0.75	0.81	0.88	1.12	1.24	1.49	1.51	1.13	1.27	1.51	1.52	ns
DIFF_HSTL_I_F	0.68	0.76	0.83	0.86	1.18	1.30	1.56	1.56	1.20	1.33	1.57	1.57	ns
DIFF_HSTL_II_F	0.68	0.76	0.83	0.86	1.21	1.33	1.59	1.59	1.23	1.36	1.60	1.60	ns
DIFF_HSTL_I_18_F	0.71	0.79	0.86	0.86	1.21	1.33	1.59	1.59	1.23	1.36	1.60	1.60	ns
DIFF_HSTL_II_18_F	0.70	0.78	0.85	0.88	1.21	1.33	1.59	1.59	1.23	1.36	1.60	1.60	ns
LVCMOS33_S4	1.26	1.34	1.41	1.52	3.80	3.93	4.18	4.18	3.82	3.96	4.20	4.20	ns
LVCMOS33_S8	1.26	1.34	1.41	1.52	3.52	3.65	3.90	3.90	3.54	3.68	3.91	3.91	ns
LVCMOS33_S12	1.26	1.34	1.41	1.52	3.09	3.21	3.46	3.46	3.10	3.24	3.48	3.48	ns
LVCMOS33_S16	1.26	1.34	1.41	1.52	3.40	3.52	3.77	3.78	3.42	3.55	3.79	3.79	ns
LVCMOS33_F4	1.26	1.34	1.41	1.52	3.26	3.38	3.64	3.64	3.28	3.41	3.65	3.65	ns
LVCMOS33_F8	1.26	1.34	1.41	1.52	2.74	2.87	3.12	3.12	2.76	2.90	3.13	3.13	ns
LVCMOS33_F12	1.26	1.34	1.41	1.52	2.56	2.68	2.93	2.93	2.57	2.71	2.95	2.95	ns
LVCMOS33_F16	1.26	1.34	1.41	1.52	2.56	2.68	2.93	3.06	2.57	2.71	2.95	3.07	ns
LVCMOS25_S4	1.12	1.20	1.27	1.38	3.13	3.26	3.51	3.51	3.15	3.29	3.52	3.52	ns
LVCMOS25_S8	1.12	1.20	1.27	1.38	2.88	3.01	3.26	3.26	2.90	3.04	3.27	3.27	ns
LVCMOS25_S12	1.12	1.20	1.27	1.38	2.48	2.60	2.85	2.85	2.49	2.63	2.87	2.87	ns
LVCMOS25_S16	1.12	1.20	1.27	1.38	2.82	2.94	3.20	3.20	2.84	2.97	3.21	3.21	ns
LVCMOS25_F4	1.12	1.20	1.27	1.38	2.74	2.87	3.12	3.12	2.76	2.90	3.13	3.13	ns
LVCMOS25_F8	1.12	1.20	1.27	1.38	2.18	2.30	2.56	2.56	2.20	2.33	2.57	2.57	ns
LVCMOS25_F12	1.12	1.20	1.27	1.38	2.16	2.29	2.54	2.54	2.18	2.32	2.55	2.56	ns
LVCMOS25_F16	1.12	1.20	1.27	1.38	2.01	2.13	2.39	2.63	2.03	2.16	2.40	2.65	ns
LVCMOS18_S4	0.74	0.83	0.89	0.97	1.62	1.74	1.99	1.99	1.63	1.77	2.01	2.01	ns
LVCMOS18_S8	0.74	0.83	0.89	0.97	2.18	2.30	2.56	2.56	2.20	2.33	2.57	2.57	ns
LVCMOS18_S12	0.74	0.83	0.89	0.97	2.18	2.30	2.56	2.56	2.20	2.33	2.57	2.57	ns
LVCMOS18_S16	0.74	0.83	0.89	0.97	1.52	1.65	1.90	1.90	1.54	1.68	1.91	1.91	ns
LVCMOS18_S24	0.74	0.83	0.89	0.97	1.60	1.72	1.98	2.40	1.62	1.75	1.99	2.41	ns
LVCMOS18_F4	0.74	0.83	0.89	0.97	1.45	1.57	1.82	1.82	1.46	1.60	1.84	1.84	ns
LVCMOS18_F8	0.74	0.83	0.89	0.97	1.68	1.80	2.06	2.06	1.70	1.83	2.07	2.07	ns
LVCMOS18_F12	0.74	0.83	0.89	0.97	1.68	1.80	2.06	2.06	1.70	1.83	2.07	2.07	ns
LVCMOS18_F16	0.74	0.83	0.89	0.97	1.40	1.52	1.77	1.78	1.42	1.55	1.79	1.79	ns

Table 54: **Input Delay Measurement Methodology *(Cont'd)***

Description	I/O Standard Attribute	V_L (1)(2)	V_H (1)(2)	V_{MEAS} (1)(4)(6)	V_{REF} (1)(3)(5)
LVDS_25, 2.5V	LVDS_25	1.2 – 0.125	1.2 + 0.125	0(6)	–
BLVDS_25, 2.5V	BLVDS_25	1.25 – 0.125	1.25 + 0.125	0(6)	–
MINI_LVDS_25, 2.5V	MINI_LVDS_25	1.25 – 0.125	1.25 + 0.125	0(6)	–
PPDS_25	PPDS_25	1.25 – 0.125	1.25 + 0.125	0(6)	–
RSDS_25	RSDS_25	1.25 – 0.125	1.25 + 0.125	0(6)	–
TMDS_33	TMDS_33	3 – 0.125	3 + 0.125	0(6)	–

Notes:

1. The input delay measurement methodology parameters for LVDCI are the same for LVCMOS standards of the same voltage. Input delay measurement methodology parameters for HSLVDCI are the same as for HSTL_II standards of the same voltage. Parameters for all other DCI standards are the same for the corresponding non-DCI standards.
2. Input waveform switches between V_L and V_H.
3. Measurements are made at typical, minimum, and maximum V_{REF} values. Reported delays reflect worst case of these measurements. V_{REF} values listed are typical.
4. Input voltage level from which measurement starts.
5. This is an input voltage reference that bears no relation to the V_{REF} / V_{MEAS} parameters found in IBIS models and/or noted in Figure 18.
6. The value given is the differential input voltage.

Output Delay Measurements

Output delays are measured with short output traces. Standard termination was used for all testing. The propagation delay of the trace is characterized separately and subtracted from the final measurement, and is therefore not included in the generalized test setups shown in Figure 18 and Figure 19.

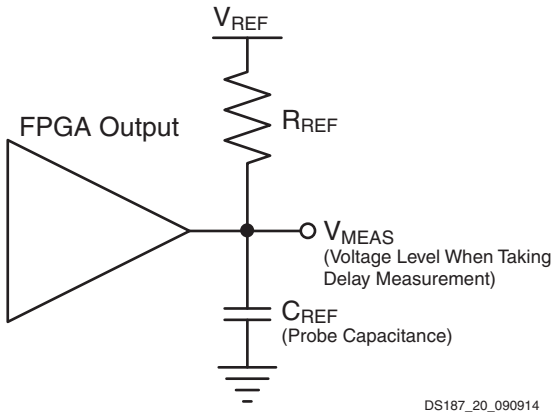

Figure 18: **Single-Ended Test Setup**

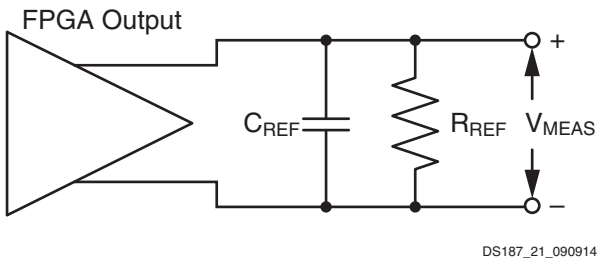

Figure 19: **Differential Test Setup**

Output Serializer/Deserializer Switching Characteristics

Table 59: **OSERDES Switching Characteristics**

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
Setup/Hold						
T_{OSDCK_D}/ T_{OSCKD_D}	D input setup/hold with respect to CLKDIV	0.42/0.03	0.45/0.03	0.63/0.03	0.63/0.08	ns
T_{OSDCK_T}/ T_{OSCKD_T}(1)	T input setup/hold with respect to CLK	0.69/–0.13	0.73/–0.13	0.88/–0.13	0.88/–0.13	ns
T_{OSDCK_T2}/ T_{OSCKD_T2}(1)	T input setup/hold with respect to CLKDIV	0.31/–0.13	0.34/–0.13	0.39/–0.13	0.39/–0.13	ns
T_{OSCCK_OCE}/ T_{OSCKC_OCE}	OCE input setup/hold with respect to CLK	0.32/0.58	0.34/0.58	0.51/0.58	0.51/0.58	ns
T_{OSCCK_S}	SR (reset) input setup with respect to CLKDIV	0.47	0.52	0.85	0.85	ns
T_{OSCCK_TCE}/ T_{OSCKC_TCE}	TCE input setup/hold with respect to CLK	0.32/0.01	0.34/0.01	0.51/0.01	0.51/0.10	ns
Sequential Delays						
T_{OSCKO_OQ}	Clock to out from CLK to OQ	0.40	0.42	0.48	0.48	ns
T_{OSCKO_TQ}	Clock to out from CLK to TQ	0.47	0.49	0.56	0.56	ns
Combinatorial						
T_{OSDO_TTQ}	T input to TQ out	0.83	0.92	1.11	1.11	ns

Notes:

1. T_{OSDCK_T2} and T_{OSCKD_T2} are reported as T_{OSDCK_T}/T_{OSCKD_T} in the timing report.

Input/Output Delay Switching Characteristics

Table 60: **Input Delay Switching Characteristics**

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
IDELAYCTRL						
T_{DLYCCO_RDY}	Reset to ready for IDELAYCTRL	3.67	3.67	3.67	3.67	µs
$F_{IDELAYCTRL\_REF}$	Attribute REFCLK frequency = 200.0(1)	200	200	200	200	MHz
	Attribute REFCLK frequency = 300.0(1)	300	300	N/A	N/A	MHz
	Attribute REFCLK frequency = 400.0(1)	400	400	N/A	N/A	MHz
IDELAYCTRL_ REF_PRECISION	REFCLK precision	±10	±10	±10	±10	MHz
$T_{IDELAYCTRL\_RPW}$	Minimum reset pulse width	59.28	59.28	59.28	59.28	ns
IDELAY						
$T_{IDELAYRESOLUTION}$	IDELAY chain delay resolution	1/(32 x 2 x F_{REF})				ps

Table 63: **CLB Distributed RAM Switching Characteristics *(Cont'd)***

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
Setup and Hold Times Before/After Clock CLK						
T_{DS_LRAM}/ T_{DH_LRAM}	A – D inputs to CLK	0.54/0.28	0.60/0.30	0.72/0.35	0.72/0.37	ns, Min
T_{AS_LRAM}/ T_{AH_LRAM}	Address An inputs to clock	0.27/0.55	0.30/0.60	0.37/0.70	0.37/0.71	ns, Min
	Address An inputs through MUXs and/or carry logic to clock	0.69/0.18	0.77/0.21	0.94/0.26	0.94/0.35	ns, Min
T_{WS_LRAM}/ T_{WH_LRAM}	WE input to clock	0.38/0.10	0.43/0.12	0.53/0.17	0.53/0.17	ns, Min
T_{CECK_LRAM}/ T_{CKCE_LRAM}	CE input to CLK	0.39/0.10	0.44/0.11	0.53/0.17	0.53/0.17	ns, Min
Clock CLK						
T_{MPW_LRAM}	Minimum pulse width	1.05	1.13	1.25	1.25	ns, Min
T_{MCP}	Minimum clock period	2.10	2.26	2.50	2.50	ns, Min

Notes:

1. T_{SHCKO} also represents the CLK to XMUX output. Refer to the timing report for the CLK to XMUX path.

CLB Shift Register Switching Characteristics (SLICEM Only)

Table 64: **CLB Shift Register Switching Characteristics**

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
Sequential Delays						
T_{REG}	Clock to A – D outputs	1.19	1.33	1.61	1.61	ns, Max
T_{REG_MUX}	Clock to AMUX – DMUX output	1.58	1.77	2.15	2.15	ns, Max
T_{REG_M31}	Clock to DMUX output via M31 output	1.12	1.23	1.46	1.46	ns, Max
Setup and Hold Times Before/After Clock CLK						
T_{WS_SHFREG}/ T_{WH_SHFREG}	WE input	0.37/0.10	0.41/0.12	0.51/0.17	0.51/0.17	ns, Min
T_{CECK_SHFREG}/ T_{CKCE_SHFREG}	CE input to CLK	0.37/0.10	0.42/0.11	0.52/0.17	0.52/0.17	ns, Min
T_{DS_SHFREG}/ T_{DH_SHFREG}	A – D inputs to CLK	0.33/0.34	0.37/0.37	0.44/0.43	0.44/0.44	ns, Min
Clock CLK						
T_{MPW_SHFREG}	Minimum pulse width	0.77	0.86	0.98	0.98	ns, Min

Block RAM and FIFO Switching Characteristics

Table 65: **Block RAM and FIFO Switching Characteristics**

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
Block RAM and FIFO Clock to Out Delays						
T_{RCKO_DO} and $T_{RCKO\_DO\_REG}$[1]	Clock CLK to DOUT output (without output register)[2][3]	1.85	2.13	2.46	2.46	ns, Max
	Clock CLK to DOUT output (with output register)[4][5]	0.64	0.74	0.89	0.89	ns, Max
$T_{RCKO\_DO\_ECC}$ and $T_{RCKO\_DO\_ECC\_REG}$	Clock CLK to DOUT output with ECC (without output register)[2][3]	2.77	3.04	3.84	3.84	ns, Max
	Clock CLK to DOUT output with ECC (with output register)[4][5]	0.73	0.81	0.94	0.94	ns, Max
$T_{RCKO\_DO\_CASCOUT}$ and $T_{RCKO\_DO\_CASCOUT\_REG}$	Clock CLK to DOUT output with cascade (without output register)[2]	2.61	2.88	3.30	3.30	ns, Max
	Clock CLK to DOUT output with cascade (with output register)[4]	1.16	1.28	1.46	1.46	ns, Max
T_{RCKO_FLAGS}	Clock CLK to FIFO flags outputs[6]	0.76	0.87	1.05	1.05	ns, Max
$T_{RCKO\_POINTERS}$	Clock CLK to FIFO pointers outputs[7]	0.94	1.02	1.15	1.15	ns, Max
$T_{RCKO\_PARITY\_ECC}$	Clock CLK to ECCPARITY in ECC encode only mode	0.78	0.85	0.94	0.94	ns, Max
$T_{RCKO\_SDBIT\_ECC}$ and $T_{RCKO\_SDBIT\_ECC\_REG}$	Clock CLK to BITERR (without output register)	2.56	2.81	3.55	3.55	ns, Max
	Clock CLK to BITERR (with output register)	0.68	0.76	0.89	0.89	ns, Max
$T_{RCKO\_RDADDR\_ECC}$ and $T_{RCKO\_RDADDR\_ECC\_REG}$	Clock CLK to RDADDR output with ECC (without output register)	0.75	0.88	1.07	1.07	ns, Max
	Clock CLK to RDADDR output with ECC (with output register)	0.84	0.93	1.08	1.08	ns, Max
Setup and Hold Times Before/After Clock CLK						
T_{RCCK_ADDRA}/ T_{RCKC_ADDRA}	ADDR inputs[8]	0.45/0.31	0.49/0.33	0.57/0.36	0.57/0.52	ns, Min
$T_{RDCK\_DI\_WF\_NC}$/ $T_{RCKD\_DI\_WF\_NC}$	Data input setup/hold time when block RAM is configured in WRITE_FIRST or NO_CHANGE mode[9]	0.58/0.60	0.65/0.63	0.74/0.67	0.74/0.67	ns, Min
$T_{RDCK\_DI\_RF}$/ $T_{RCKD\_DI\_RF}$	Data input setup/hold time when block RAM is configured in READ_FIRST mode[9]	0.20/0.29	0.22/0.34	0.25/0.41	0.25/0.50	ns, Min
$T_{RDCK\_DI\_ECC}$/ $T_{RCKD\_DI\_ECC}$	DIN inputs with block RAM ECC in standard mode[9]	0.50/0.43	0.55/0.46	0.63/0.50	0.63/0.50	ns, Min
	DIN inputs with block RAM ECC encode only[9]	0.93/0.43	1.02/0.46	1.17/0.50	1.17/0.50	ns, Min
	DIN inputs with FIFO ECC in standard mode[9]	1.04/0.56	1.15/0.59	1.32/0.64	1.32/0.64	ns, Min
$T_{RDCK\_DI\_ECCW}$/ $T_{RCKD\_DI\_ECCW}$	DIN inputs with block RAM ECC encode only[9]	0.93/0.43	1.02/0.46	1.17/0.50	1.17/0.50	ns, Min
$T_{RDCK\_DI\_ECC\_FIFO}$/ $T_{RCKD\_DI\_ECC\_FIFO}$	DIN inputs with FIFO ECC in standard mode[9]	1.04/0.56	1.15/0.59	1.32/0.64	1.32/0.64	ns, Min
$T_{RCCK\_INJECTBITERR}$/ $T_{RCKC\_INJECTBITERR}$	Inject single/double bit error in ECC mode	0.58/0.35	0.64/0.37	0.74/0.40	0.74/0.52	ns, Min

Table 65: **Block RAM and FIFO Switching Characteristics *(Cont'd)***

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
T_{RCCK_EN}/ T_{RCKC_EN}	Block RAM enable (EN) input	0.35/0.20	0.39/0.21	0.45/0.23	0.45/0.41	ns, Min
T_{RCCK_REGCE}/ T_{RCKC_REGCE}	CE input of output register	0.24/0.15	0.29/0.15	0.36/0.16	0.36/0.39	ns, Min
T_{RCCK_RSTREG}/ T_{RCKC_RSTREG}	Synchronous RSTREG input	0.29/0.07	0.32/0.07	0.35/0.07	0.35/0.17	ns, Min
T_{RCCK_RSTRAM}/ T_{RCKC_RSTRAM}	Synchronous RSTRAM input	0.32/0.42	0.34/0.43	0.36/0.46	0.36/0.57	ns, Min
T_{RCCK_WEA}/ T_{RCKC_WEA}	Write enable (WE) input (block RAM only)	0.44/0.18	0.48/0.19	0.54/0.20	0.54/0.42	ns, Min
T_{RCCK_WREN}/ T_{RCKC_WREN}	WREN FIFO inputs	0.46/0.30	0.46/0.35	0.47/0.43	0.47/0.43	ns, Min
T_{RCCK_RDEN}/ T_{RCKC_RDEN}	RDEN FIFO inputs	0.42/0.30	0.43/0.35	0.43/0.43	0.43/0.62	ns, Min
Reset Delays						
T_{RCO_FLAGS}	Reset RST to FIFO flags/pointers(10)	0.90	0.98	1.10	1.10	ns, Max
T_{RREC_RST}/ T_{RREM_RST}	FIFO reset recovery and removal timing(11)	1.87/–0.81	2.07/–0.81	2.37/–0.81	2.37/–0.58	ns, Max
Maximum Frequency						
$F_{MAX\_BRAM\_WF\_NC}$	Block RAM (write first and no change modes) When not in SDP RF mode.	509.68	460.83	388.20	388.20	MHz
$F_{MAX\_BRAM\_RF\_PERFORMANCE}$	Block RAM (read first, performance mode) When in SDP RF mode but no address overlap between port A and port B.	509.68	460.83	388.20	388.20	MHz
$F_{MAX\_BRAM\_RF\_DELAYED\_WRITE}$	Block RAM (read first, delayed write mode) When in SDP RF mode and there is possibility of overlap between port A and port B addresses.	447.63	404.53	339.67	339.67	MHz
$F_{MAX\_CAS\_WF\_NC}$	Block RAM cascade (write first, no change mode) When cascade but not in RF mode.	467.07	418.59	345.78	345.78	MHz
$F_{MAX\_CAS\_RF\_PERFORMANCE}$	Block RAM cascade (read first, performance mode) When in cascade with RF mode and no possibility of address overlap/one port is disabled.	467.07	418.59	345.78	345.78	MHz
$F_{MAX\_CAS\_RF\_DELAYED\_WRITE}$	When in cascade RF mode and there is a possibility of address overlap between port A and port B.	405.35	362.19	297.35	297.35	MHz

Clock Buffers and Networks

Table 67: **Global Clock Switching Characteristics (Including BUFGCTRL)**

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
$T_{BCCCK\_CE}/T_{BCCKC\_CE}$(1)	CE pins setup/hold	0.13/0.39	0.14/0.41	0.18/0.42	0.18/0.84	ns
T_{BCCCK_S}/T_{BCCKC_S}(1)	S pins setup/hold	0.13/0.39	0.14/0.41	0.18/0.42	0.18/0.84	ns
T_{BCCKO_O}(2)	BUFGCTRL delay from I0/I1 to O	0.08	0.09	0.11	0.11	ns
Maximum Frequency						
F_{MAX_BUFG}	Global clock tree (BUFG)	628.00	628.00	464.00	464.00	MHz

Notes:

1. T_{BCCCK_CE} and T_{BCCKC_CE} must be satisfied to assure glitch-free operation of the global clock when switching between clocks. These parameters do not apply to the BUFGMUX primitive that assures glitch-free operation. The other global clock setup and hold times are optional; only needing to be satisfied if device operation requires simulation matches on a cycle-for-cycle basis when switching between clocks.
2. T_{BGCKO_O} (BUFG delay from I0 to O) values are the same as T_{BCCKO_O} values.

Table 68: **Input/Output Clock Switching Characteristics (BUFIO)**

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
T_{BIOCKO_O}	Clock to out delay from I to O	1.16	1.32	1.61	1.61	ns
Maximum Frequency						
F_{MAX_BUFIO}	I/O clock tree (BUFIO)	680.00	680.00	600.00	600.00	MHz

Table 69: **Regional Clock Buffer Switching Characteristics (BUFR)**

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
T_{BRCKO_O}	Clock to out delay from I to O	0.64	0.80	1.04	1.04	ns
$T_{BRCKO\_O\_BYP}$	Clock to out delay from I to O with Divide Bypass attribute set	0.35	0.41	0.54	0.54	ns
T_{BRDO_O}	Propagation delay from CLR to O	0.85	0.89	1.14	1.14	ns
Maximum Frequency						
F_{MAX_BUFR}(1)	Regional clock tree (BUFR)	420.00	375.00	315.00	315.00	MHz

Notes:

1. The maximum input frequency to the BUFR and BUFMR is the BUFIO F_{MAX} frequency.

Table 70: **Horizontal Clock Buffer Switching Characteristics (BUFH)**

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
T_{BHCKO_O}	BUFH delay from I to O	0.11	0.11	0.14	0.14	ns
$T_{BHCCK\_CE}/T_{BHCKC\_CE}$	CE pin setup and hold	0.20/0.13	0.23/0.16	0.29/0.21	0.29/0.43	ns
Maximum Frequency						
F_{MAX_BUFH}	Horizontal clock buffer (BUFH)	628.00	628.00	464.00	464.00	MHz

PLL Switching Characteristics

Table 73: **PLL Specification**

Symbol	Description	Speed Grade				Units
		-3	-2	-1C/-1I/-1LI	-1Q	
PLL_F_{INMAX}	Maximum input clock frequency	800.00	800.00	800.00	800.00	MHz
PLL_F_{INMIN}	Minimum input clock frequency	19.00	19.00	19.00	19.00	MHz
PLL_$F_{INJITTER}$	Maximum input clock period jitter	< 20% of clock input period or 1 ns Max				
PLL_F_{INDUTY}	Allowable input duty cycle: 19—49 MHz	25	25	25	25	%
	Allowable input duty cycle: 50—199 MHz	30	30	30	30	%
	Allowable input duty cycle: 200—399 MHz	35	35	35	35	%
	Allowable input duty cycle: 400—499 MHz	40	40	40	40	%
	Allowable input duty cycle: >500 MHz	45	45	45	45	%
PLL_F_{VCOMIN}	Minimum PLL VCO frequency	800.00	800.00	800.00	800.00	MHz
PLL_F_{VCOMAX}	Maximum PLL VCO frequency	2133.00	1866.00	1600.00	1600.00	MHz
PLL_$F_{BANDWIDTH}$	Low PLL bandwidth at typical(1)	1.00	1.00	1.00	1.00	MHz
	High PLL bandwidth at typical(1)	4.00	4.00	4.00	4.00	MHz
PLL_$T_{STATPHAOFFSET}$	Static phase offset of the PLL outputs(2)	0.12	0.12	0.12	0.12	ns
PLL_$T_{OUTJITTER}$	PLL output jitter	Note 3				
PLL_$T_{OUTDUTY}$	PLL output clock duty-cycle precision(4)	0.20	0.20	0.20	0.20	ns
PLL_$T_{LOCKMAX}$	PLL maximum lock time	100.00	100.00	100.00	100.00	µs
PLL_F_{OUTMAX}	PLL maximum output frequency	800.00	800.00	800.00	800.00	MHz
PLL_F_{OUTMIN}	PLL minimum output frequency(5)	6.25	6.25	6.25	6.25	MHz
PLL_$T_{EXTFDVAR}$	External clock feedback variation	< 20% of clock input period or 1 ns Max				
PLL_$RST_{MINPULSE}$	Minimum reset pulse width	5.00	5.00	5.00	5.00	ns
PLL_F_{PFDMAX}	Maximum frequency at the phase frequency detector	550.00	500.00	450.00	450.00	MHz
PLL_F_{PFDMIN}	Minimum frequency at the phase frequency detector	19.00	19.00	19.00	19.00	MHz
PLL_$T_{FBDELAY}$	Maximum delay in the feedback path	3 ns Max or one CLKIN cycle				
Dynamic Reconfiguration Port (DRP) for PLL Before and After DCLK						
$T_{PLLCCK\_DADDR}/T_{PLLCKC\_DADDR}$	Setup and hold of D address	1.25/0.15	1.40/0.15	1.63/0.15	1.63/0.15	ns, Min
$T_{PLLCCK\_DI}/T_{PLLCKC\_DI}$	Setup and hold of D input	1.25/0.15	1.40/0.15	1.63/0.15	1.63/0.15	ns, Min
$T_{PLLCCK\_DEN}/T_{PLLCKC\_DEN}$	Setup and hold of D enable	1.76/0.00	1.97/0.00	2.29/0.00	2.29/0.00	ns, Min
$T_{PLLCCK\_DWE}/T_{PLLCKC\_DWE}$	Setup and hold of D write enable	1.25/0.15	1.40/0.15	1.63/0.15	1.63/0.15	ns, Min
T_{PLLCKO_DRDY}	CLK to out of DRDY	0.65	0.72	0.99	0.99	ns, Max
F_{DCK}	DCLK frequency	200.00	200.00	200.00	200.00	MHz, Max

Notes:

1. The PLL does not filter typical spread-spectrum input clocks because they are usually far below the bandwidth filter frequencies.
2. The static offset is measured between any PLL outputs with identical phase.
3. Values for this parameter are available in the Clocking Wizard. See http://www.xilinx.com/products/intellectual-property/clocking_wizard.htm.
4. Includes global clock buffer.
5. Calculated as $F_{VCO}/128$ assuming output duty cycle is 50%.

Device Pin-to-Pin Output Parameter Guidelines

Table 74: **Clock-Capable Clock Input to Output Delay Without MMCM/PLL (Near Clock Region)(1)**

Symbol	Description	Device	Speed Grade				Units
			-3	-2	-1C/-1I/-1LI	-1Q	
SSTL15 Clock-Capable Clock Input to Output Delay using Output Flip-Flops, Fast Slew Rate, *without* MMCM/PLL.							
T_{ICKOF}	Clock-capable clock input and OUTFF at pins/banks closest to the BUFGs *without* MMCM/PLL (near clock region)(2)	XC7Z007S	N/A	5.68	6.65	N/A	ns
		XC7Z012S	N/A	5.96	6.90	N/A	ns
		XC7Z014S	N/A	6.05	7.08	N/A	ns
		XC7Z010	5.08	5.68	6.65	N/A	ns
		XC7Z015	5.34	5.96	6.90	N/A	ns
		XC7Z020	5.42	6.05	7.08	N/A	ns
		XA7Z010	N/A	N/A	6.65	6.65	ns
		XA7Z020	N/A	N/A	7.08	7.08	ns
		XQ7Z020	N/A	6.05	7.08	7.08	ns

Notes:

1. This table lists representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Refer to the *Die Level Bank Numbering Overview* section of *Zynq-7000 All Programmable SoC Packaging and Pinout Specification* (UG865).

Table 75: **Clock-Capable Clock Input to Output Delay Without MMCM/PLL (Far Clock Region)(1)**

Symbol	Description	Device	Speed Grade				Units
			-3	-2	-1C/-1I/-1LI	-1Q	
SSTL15 Clock-Capable Clock Input to Output Delay using Output Flip-Flops, Fast Slew Rate, *without* MMCM/PLL.							
$T_{ICKOFFAR}$	Clock-capable clock input and OUTFF at pins/banks farthest from the BUFGs *without* MMCM/PLL (far clock region)(2)	XC7Z007S	N/A	5.68	6.65	N/A	ns
		XC7Z012S	N/A	6.25	7.21	N/A	ns
		XC7Z014S	N/A	6.34	7.40	N/A	ns
		XC7Z010	5.08	5.68	6.65	N/A	ns
		XC7Z015	5.60	6.25	7.21	N/A	ns
		XC7Z020	5.69	6.34	7.40	N/A	ns
		XA7Z010	N/A	N/A	6.65	6.65	ns
		XA7Z020	N/A	N/A	7.40	7.40	ns
		XQ7Z020	N/A	6.34	7.40	7.40	ns

Notes:

1. This table lists representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Refer to the *Die Level Bank Numbering Overview* section of *Zynq-7000 All Programmable SoC Packaging and Pinout Specification* (UG865).

GTP Transceiver Specifications (Only available in the XC7Z012S and XC7Z015)

GTP Transceiver DC Input and Output Levels

Table 85 summarizes the DC output specifications of the GTP transceivers in the XC7Z012S and XC7Z015. Consult the *7 Series FPGAs GTP Transceiver User Guide* (UG482) for further details.

Table 85: **GTP Transceiver DC Specifications**

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
DV_{PPOUT}	Differential peak-to-peak output voltage(1)	Transmitter output swing is set to maximum setting	1000	–	–	mV
$V_{CMOUTDC}$	DC common mode output voltage	Equation based	$V_{MGTAVTT} - DV_{PPOUT}/4$			mV
R_{OUT}	Differential output resistance		–	100	–	Ω
$V_{CMOUTAC}$	Common mode output voltage: AC coupled		1/2 $V_{MGTAVTT}$			mV
T_{OSKEW}	Transmitter output pair (TXP and TXN) intra-pair skew		–	–	12	ps
DV_{PPIN}	Differential peak-to-peak input voltage	External AC coupled	150	–	2000	mV
V_{IN}	Single-ended input voltage(2)	DC coupled $V_{MGTAVTT}$ = 1.2V	–200	–	$V_{MGTAVTT}$	mV
V_{CMIN}	Common mode input voltage	DC coupled $V_{MGTAVTT}$ = 1.2V	–	2/3 $V_{MGTAVTT}$	–	mV
R_{IN}	Differential input resistance		–	100	–	Ω
C_{EXT}	Recommended external AC coupling capacitor(3)		–	100	–	nF

Notes:

1. The output swing and preemphasis levels are programmable using the attributes discussed in the *7 Series FPGAs GTP Transceiver User Guide* (UG482) and can result in values lower than reported in this table.
2. Voltage measured at the pin referenced to GND.
3. Other values can be used as appropriate to conform to specific protocols and standards.

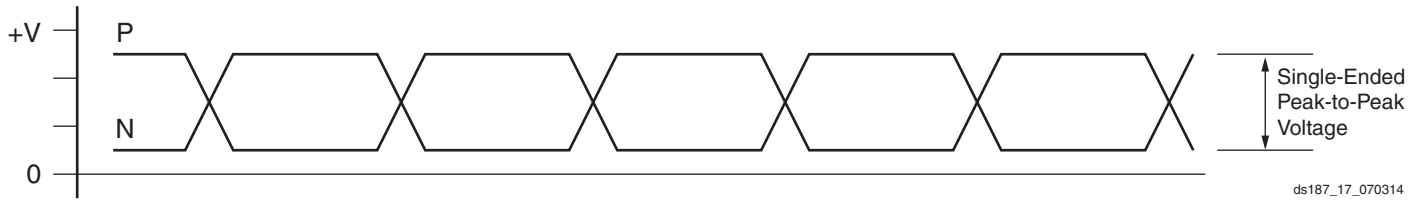

Figure 20: **Single-Ended Peak-to-Peak Voltage**

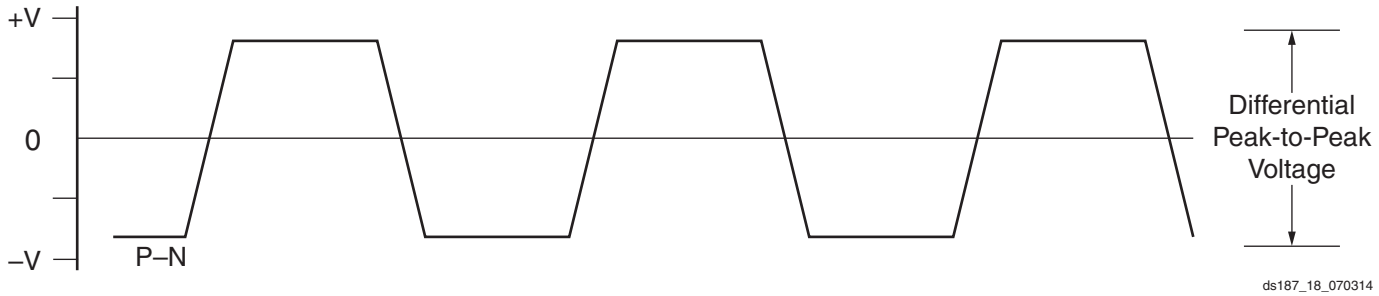

Figure 21: **Differential Peak-to-Peak Voltage**

Note: In Figure 21, differential peak-to-peak voltage = single-ended peak-to-peak voltage x 2.

GTP Transceiver Protocol Jitter Characteristics

For Table 94 through Table 98, the *7 Series FPGAs GTP Transceiver User Guide* (UG482) contains recommended settings for optimal usage of protocol specific characteristics.

Table 94: **Gigabit Ethernet Protocol Characteristics**

Description	Line Rate (Mb/s)	Min	Max	Units
Gigabit Ethernet Transmitter Jitter Generation				
Total transmitter jitter (T_TJ)	1250	–	0.24	UI
Gigabit Ethernet Receiver High Frequency Jitter Tolerance				
Total receiver jitter tolerance	1250	0.749	–	UI

Table 95: **XAUI Protocol Characteristics**

Description	Line Rate (Mb/s)	Min	Max	Units
XAUI Transmitter Jitter Generation				
Total transmitter jitter (T_TJ)	3125	–	0.35	UI
XAUI Receiver High Frequency Jitter Tolerance				
Total receiver jitter tolerance	3125	0.65	–	UI

Table 96: **PCI Express Protocol Characteristics(1)**

Standard	Description	Line Rate (Mb/s)	Min	Max	Units
PCI Express Transmitter Jitter Generation					
PCI Express Gen 1	Total transmitter jitter	2500	–	0.25	UI
PCI Express Gen 2	Total transmitter jitter	5000	–	0.25	UI
PCI Express Receiver High Frequency Jitter Tolerance					
PCI Express Gen 1	Total receiver jitter tolerance	2500	0.65	–	UI
PCI Express Gen 2(2)	Receiver inherent timing error	5000	0.40	–	UI
	Receiver inherent deterministic timing error		0.30	–	UI

Notes:

1. Tested per card electromechanical (CEM) methodology.
2. Using common REFCLK.

Table 97: **CEI-6G Protocol Characteristics**

Description	Line Rate (Mb/s)	Interface	Min	Max	Units
CEI-6G Transmitter Jitter Generation					
Total transmitter jitter(1)	4976–6375	CEI-6G-SR	–	0.3	UI
CEI-6G Receiver High Frequency Jitter Tolerance					
Total receiver jitter tolerance(1)	4976–6375	CEI-6G-SR	0.6	–	UI

Notes:

1. Tested at most commonly used line rate of 6250 Mb/s using 390.625 MHz reference clock.

XADC Specifications

Table 100: **XADC Specifications**

Parameter	Symbol	Comments/Conditions	Min	Typ	Max	Units
V_{CCADC} = 1.8V ± 5%, V_{REFP} = 1.25V, V_{REFN} = 0V, ADCCLK = 26 MHz, –55°C ≤ T_j ≤ 125°C, Typical values at T_j=+40°C						
ADC Accuracy(1)						
Resolution			12	–	–	Bits
Integral Nonlinearity(2)	INL	–40°C ≤ T_j ≤ 100°C	–	–	±2	LSBs
		–55°C ≤ T_j < –40°C; 100°C < T_j ≤ 125°C	–	–	±3	LSBs
Differential Nonlinearity	DNL	No missing codes, guaranteed monotonic	–	–	±1	LSBs
Offset Error	Unipolar	–40°C ≤ T_j ≤ 100°C	–	–	±8	LSBs
		–55°C ≤ T_j < –40°C; 100°C < T_j ≤ 125°C			±12	LSBs
	Bipolar	–55°C ≤ T_j ≤ 125°C	–	–	±4	LSBs
Gain Error			–	–	±0.5	%
Offset Matching			–	–	4	LSBs
Gain Matching			–	–	0.3	%
Sample Rate			–	–	1	MS/s
Signal to Noise Ratio(2)	SNR	F_{SAMPLE} = 500KS/s, F_{IN} = 20KHz	60	–	–	dB
RMS Code Noise		External 1.25V reference	–	–	2	LSBs
		On-chip reference	–	3	–	LSBs
Total Harmonic Distortion(2)	THD	F_{SAMPLE} = 500KS/s, F_{IN} = 20KHz	70	–	–	dB
Analog Inputs(3)						
ADC Input Ranges		Unipolar operation	0	–	1	V
		Bipolar operation	–0.5	–	+0.5	V
		Unipolar common mode range (FS input)	0	–	+0.5	V
		Bipolar common mode range (FS input)	+0.5	–	+0.6	V
Maximum External Channel Input Ranges		Adjacent analog channels set within these ranges should not corrupt measurements on adjacent channels	–0.1	–	V_{CCADC}	V
Auxiliary Channel Full Resolution Bandwidth	FRBW		250	–	–	KHz
On-Chip Sensors						
Temperature Sensor Error		–40°C ≤ T_j ≤ 100°C	–	–	±4	°C
		–55°C ≤ T_j < –40°C; 100°C < T_j ≤ 125°C	–	–	±6	°C
Supply Sensor Error		–40°C ≤ T_j ≤ 100°C	–	–	±1	%
		–55°C ≤ T_j < –40°C; 100°C < T_j ≤ 125°C	–	–	±2	%
Conversion Rate(4)						
Conversion Time - Continuous	t_{CONV}	Number of ADCCLK cycles	26	–	32	Cycles
Conversion Time - Event	t_{CONV}	Number of CLK cycles	–	–	21	Cycles
DRP Clock Frequency	DCLK	DRP clock frequency	8	–	250	MHz
ADC Clock Frequency	ADCCLK	Derived from DCLK	1	–	26	MHz
DCLK Duty Cycle			40	–	60	%

Date	Version	Description of Revisions
02/14/2013	1.4	Corrected $T_{QSPICKD2}$ minimum equation in Table 34. Updated timing parameter names in Figure 4 and Figure 5 to match those in the accompanying table.
02/19/2013	1.4.1	Corrected version history.
03/19/2013	1.5	Updated Table 15 and Table 16 to the product status of production for the XC7Z010 devices with -2 and -1 speed specifications. Updated Figure 4 by adding OUT0. Added Note 2 to Table 33. Added Table 38 and Figure 9.
04/24/2013	1.6	All the devices listed in this data sheet are production released. Updated the AC Switching Characteristics based upon ISE tools 14.5 and Vivado tools 2013.1, both at v1.06 for the -3, -2, and -1 speed specifications throughout the document. Updated Table 15 and Table 16 for production release of the XC7Z010 and XC7Z020 in the -3 speed designations. Removed the *PS Power-on Reset* section. Updated the PS—PL Power Sequencing section. In Table 1, revised V_{IN} (I/O input voltage) to match values in Table 4, and combined Note 4 with old Note 5 and then added new Note 6. Revised V_{IN} description and added Note 8 in Table 2. Updated first 3 rows in Table 4. Revised PCI33_3 voltage minimum in Table 10 to match values in Table 1 and Table 4. Added Note 1 to Table 13. Clarified the load conditions in Table 34 by adding new data. Clarified title of Table 51. Throughout the data sheet (Table 62, Table 63, Table 64, and Table 79) removed the obvious note "A Zero "0" Hold Time listing indicates no hold time or a negative hold time."
07/08/2013	1.7	Added Note 5 to Table 2. Revised the frequency of CPU clock performance (6:2:1) in Table 17. Updated F_{DDR3L_MAX} values in Table 18. Moved and added F_{AXI_MAX} to Table 19. Updated the minimum $T_{DQVALID}$ values in Table 25 and Table 26. In Table 37, corrected the F_{SDSCLK} maximum value. In Table 38, corrected F_{SDSCLK} and fixed the $F_{SDIDCLK}$ typographical unit error. Values in Table 78 and Table 82 were reported incorrectly and have been updated to match speed specifications.
09/12/2013	1.8	Added the XC7Z015 throughout the document. The XC7Z015 is the only device in this data sheet that includes GTP transceivers. Added the GTP transceivers specifications to Table 1, Table 2, and Table 7, and the PL Power-On/Off Power Supply Sequencing, PS—PL Power Sequencing, GTP Transceiver Specifications (Only available in the XC7Z012S and XC7Z015), Integrated Interface Block for PCI Express Designs Switching Characteristics (XC7Z012S and XC7Z015 Only) and sections. Added USRCCLK Output section and clarified values for T_{POR} in Table 101. Added I_{PSFS} to Table 102. Updated Notice of Disclaimer.
11/26/2013	1.9	Added specifications for the XQ7Z020 with the -1Q speed specification/temperature range. Added specifications for the XA7Z010 and XA7Z020 with the -1Q speed specification/temperature range. Removed Note 1 and Note 2 from Table 6. Added Table 14. Updated Table 100 specifications. In Table 101, removed the USRCCLK Output section, added T_{PL}, $T_{PROGRAM}$, Note 1, and the Device DNA Access Port section, and updated the T_{POR} description.
01/20/2014	1.10	Update Note 7 in Table 2. Added Note 2 to Table 4. Updated speed files in data sheet and Table 14. Updated Table 15 and Table 16 for production release of the XA7Z010 and XA7Z020 in the -1I and -1Q speed designations. Added I/O standards to Table 52 and improved all of the T_{IOTP} speed specifications.
02/25/2014	1.11	Production release of the XC7Z015 for all speed specifications and temperature ranges, including finalizing information in Table 15 and Table 16. Added XC7Z015 data to Table 5, Table 6, and Table 71. Added Table 27.
07/14/2014	1.12	In Table 4, updated Note 2 per the customer notice *7 Series FPGA and Zynq-7000 AP SoC I/O Undershoot Voltage Data Sheet Update* (XCN14014). Added heading LVDS DC Specifications (LVDS_25). Fixed units for T_{DQSS} in Table 27. Updated heading Input/Output Delay Switching Characteristics. Updated $F_{IDELAYCTRL\_REF}$, $T_{IDELAYPAT\_JIT}$ and $T_{ODELAYPAT\_JIT}$, and Note 1 in Table 60. Removed note from Table 62. Updated description of T_{ICKOF} and added Note 2 to Table 74. Updated description of $T_{ICKOFFAR}$ and added Note 2 to Table 75. Revised DV_{PPOUT} and V_{IN}, and added Note 2 to Table 85. Revised labels in Figure 20 and Figure 21 and added a note after Figure 21. Added Note 1 to Table 99.
10/09/2014	1.13	Added -1LI speed grade throughout. Updated Introduction. Removed 3.3V as descriptor of HR I/O banks throughout. In PL Power-On/Off Power Supply Sequencing, added sentence about there being no recommended sequence for supplies not shown. In PS—PL Power Sequencing, removed list of PL power supplies. In Table 20, removed typical value and added maximum value for $T_{RFPSCLK}$. Added note about measurement being taken from V_{REF} to V_{REF} in Table 25 to Table 32. Added I/O Standard Adjustment Measurement Methodology.

Date	Version	Description of Revisions
11/19/2014	1.14	Added V_{CCBRAM} to Introduction. Replaced -1L speed grade with -1LI and removed 1.0V row for V_{CCINT} and V_{CCBRAM} in Table 2. Updated the AC Switching Characteristics based upon Vivado 2014.4. Updated Vivado software version in Table 14. In Table 15, moved -1LI speed grade for XC7Z010, XC7Z015, and XC7Z020 devices from Advance to Production. In Table 16, added Vivado 2013.1 software version to -2E, -2I, -1C, and -1I speed grades of XC7Z010 and XC7Z020 devices, added Vivado 2014.4 software version to -1LI speed grade for all commercial devices, and removed table note. Added Selecting the Correct Speed Grade and Voltage in the Vivado Tools. Added Note 1 to Table 49. In Table 51, moved LPDDR2 row to end of 2:1 Memory Controllers section.
02/23/2015	1.15	Updated descriptions of V_{CCPINT} in Table 1 and Table 2. Added Note 6 to Table 11. In Table 13, changed maximum V_{ICM} value from 1.425V to 1.500V. Updated Table 22 title. Added Figure 1 and Table 23. In Table 34, updated minimum $T_{QSPIDCK2}$ and $T_{QSPICKD2}$ to 6 ns and 12.5 ns, respectively, and removed note 5. In Table 65, added $T_{RDCK\_DI\_ECCW}$/$T_{RCKD\_DI\_ECCW}$ and $T_{RDCK\_DI\_ECC\_FIFO}$/ $T_{RCKD\_DI\_ECC\_FIFO}$, updated T_{RCCK_EN}/T_{RCKC_EN} symbols, and updated Note 1. In Table 66, updated $T_{DSPDCK\_\{A, B\}\_MREG\_MULT}$/$T_{DSPCKD\_\{A, B\}\_MREG\_MULT}$ and $T_{DSPDCK\_\{A, D\}\_ADREG}$/ $T_{DSPCKD\_\{A, D\}\_ADREG}$ symbols, and replaced B input with A input for $T_{DSPDO\_A\_P}$. Removed minimum sample rate specification from Table 100.
09/22/2015	1.16	Updated data sheet per the customer notice XCN15034: *Zynq-7000 AP SoC Requirement for the PS Power-Off Sequence*. Assigned quiescent supply currents to -1LI speed grade XQ7Z020 device in Table 5. Updated PS Power-On/Off Power Supply Sequencing. Removed N/A from -1LI speed gradeXQ7Z020 device production software cell in Table 16. Added $F_{SMC\_REF\_CLK}$ to Table 33.
11/24/2015	1.17	Updated the AC Switching Characteristics based upon Vivado 2015.4. In Table 15, added -1LI speed grade to Production column for XQ7Z020. In Table 16, added Vivado 2015.4 software version to -1LI speed grade column for XQ7Z020. In Figure 4 and Figure 5, added extra clock pulse on QSPI_SCLK_OUT.
07/26/2016	1.18	Updated first sentence in PS Power-On/Off Power Supply Sequencing. Added T_{PSPOR} to Note 1 in Table 22. In Table 54, changed V_{MEAS} for LVCMOS (3.3V), LVTTL (3.3V), and PCI33 (3.3V) to 1.65V.
10/03/2016	1.19	Added XC7Z007S, XC7Z012S, and XC7Z014S throughout. Updated the AC Switching Characteristics based upon Vivado 2016.3.

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